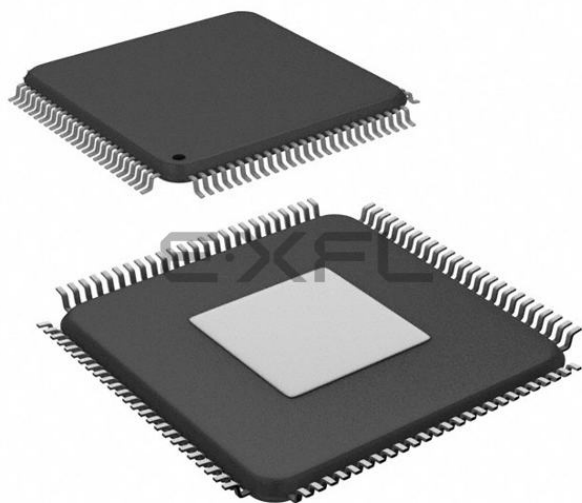




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Details

Product Status	Not For New Designs
Core Processor	C166SV2
Core Size	16-Bit
Speed	66MHz
Connectivity	CANbus, EBI/EMI, I ² C, LINbus, SPI, SSC, UART/USART, USI
Peripherals	I ² S, POR, PWM, WDT
Number of I/O	75
Program Memory Size	384KB (384K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	34K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP Exposed Pad
Supplier Device Package	PG-LQFP-100-3
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xe164f48f66lacfxuma1

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Summary of Features

The XE164 types are offered with several Flash memory sizes. **Table 2** describes the location of the available memory areas for each Flash memory size.

Table 2 Flash Memory Allocation

Total Flash Size	Flash Area A¹⁾	Flash Area B	Flash Area C
768 Kbytes	C0'0000 _H ... C0'FFFF _H	C1'0000 _H ... CB'FFFF _H	n.a.
576 Kbytes	C0'0000 _H ... C0'FFFF _H	C1'0000 _H ... C8'FFFF _H	n.a.
384 Kbytes	C0'0000 _H ... C0'FFFF _H	C1'0000 _H ... C5'FFFF _H	n.a.
192 Kbytes	C0'0000 _H ... C0'FFFF _H	C1'0000 _H ... C1'FFFF _H	C4'0000 _H ... C4'FFFF _H

1) The uppermost 4-Kbyte sector of the first Flash segment is reserved for internal use (C0'F000_H to C0'FFFF_H).

The XE164 types are offered with different interface options. **Table 3** lists the available channels for each option.

Table 3 Interface Channel Association

Total Number	Available Channels
11 ADC0 channels	CH0, CH2 ... CH5, CH8 ... CH11, CH13, CH15
6 ADC0 channels	CH0, CH2, CH3, CH4, CH5, CH8
5 ADC1 channels	CH0, CH2, CH4, CH5, CH6
4 CAN nodes	CAN0, CAN1, CAN2, CAN3
2 CAN nodes	CAN0, CAN1
6 serial channels	U0C0, U0C1, U1C0, U1C1, U2C0, U2C1
4 serial channels	U0C0, U0C1, U1C0, U1C1

2 General Device Information

The XE164 series of real time signal controllers is a part of the Infineon XE166 Family of full-feature single-chip CMOS microcontrollers. These devices extend the functionality and performance of the C166 Family in terms of instructions (MAC unit), peripherals, and speed. They combine high CPU performance (up to 80 million instructions per second) with extended peripheral functionality and enhanced IO capabilities. Optimized peripherals can be adapted flexibly to meet the application requirements. These derivatives utilize clock generation via PLL and internal or external clock sources. On-chip memory modules include program Flash, program RAM, and data RAM.

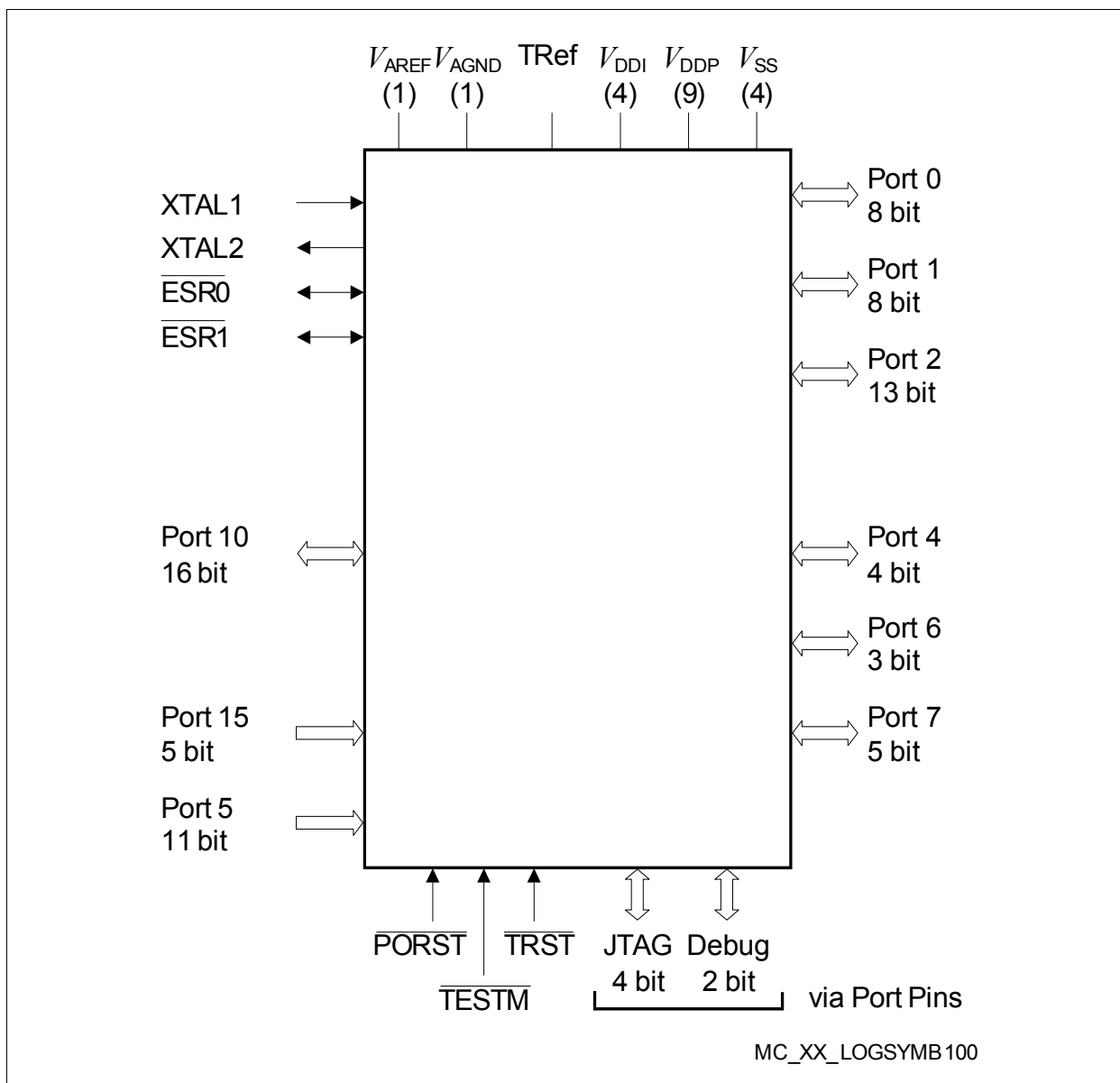


Figure 1 **Logic Symbol**

Table 4 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
12	P6.1	O0 / I	St/A	Bit 1 of Port 6, General Purpose Input/Output
	EMUX1	O1	St/A	External Analog MUX Control Output 1 (ADC0)
	T3OUT	O2	St/A	GPT1 Timer T3 Toggle Latch Output
	U1C1_DOUT	O3	St/A	USIC1 Channel 1 Shift Data Output
	ADCx_REQTRyC	I	St/A	External Request Trigger Input for ADC0/1
13	P6.2	O0 / I	St/A	Bit 2 of Port 6, General Purpose Input/Output
	EMUX2	O1	St/A	External Analog MUX Control Output 2 (ADC0)
	T6OUT	O2	St/A	GPT2 Timer T6 Toggle Latch Output
	U1C1_SCLKOUT	O3	St/A	USIC1 Channel 1 Shift Clock Output
	U1C1_DX1C	I	St/A	USIC1 Channel 1 Shift Clock Input
15	P15.0	I	In/A	Bit 0 of Port 15, General Purpose Input
	ADC1_CH0	I	In/A	Analog Input Channel 0 for ADC1
16	P15.2	I	In/A	Bit 2 of Port 15, General Purpose Input
	ADC1_CH2	I	In/A	Analog Input Channel 2 for ADC1
	T5IN	I	In/A	GPT2 Timer T5 Count/Gate Input
17	P15.4	I	In/A	Bit 4 of Port 15, General Purpose Input
	ADC1_CH4	I	In/A	Analog Input Channel 4 for ADC1
	T6IN	I	In/A	GPT2 Timer T6 Count/Gate Input
18	P15.5	I	In/A	Bit 5 of Port 15, General Purpose Input
	ADC1_CH5	I	In/A	Analog Input Channel 5 for ADC1
	T6EUD	I	In/A	GPT2 Timer T6 External Up/Down Control Input
19	P15.6	I	In/A	Bit 6 of Port 15, General Purpose Input
	ADC1_CH6	I	In/A	Analog Input Channel 6 for ADC1
20	V_{AREF}	-	PS/A	Reference Voltage for A/D Converters ADC0/1
21	V_{AGND}	-	PS/A	Reference Ground for A/D Converters ADC0/1
22	P5.0	I	In/A	Bit 0 of Port 5, General Purpose Input
	ADC0_CH0	I	In/A	Analog Input Channel 0 for ADC0

Table 4 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
35	P5.15	I	In/A	Bit 15 of Port 5, General Purpose Input
	ADC0_CH15	I	In/A	Analog Input Channel 15 for ADC0
36	P2.12	O0 / I	St/B	Bit 12 of Port 2, General Purpose Input/Output
	U0C0_SELO4	O1	St/B	USIC0 Channel 0 Select/Control 4 Output
	U0C1_SELO3	O2	St/B	USIC0 Channel 1 Select/Control 3 Output
	READY	I	St/B	External Bus Interface READY Input
37	P2.11	O0 / I	St/B	Bit 11 of Port 2, General Purpose Input/Output
	U0C0_SELO2	O1	St/B	USIC0 Channel 0 Select/Control 2 Output
	U0C1_SELO2	O2	St/B	USIC0 Channel 1 Select/Control 2 Output
	$\overline{\text{BHE}}/\text{WRH}$	OH	St/B	External Bus Interf. High-Byte Control Output Can operate either as Byte High Enable ($\overline{\text{BHE}}$) or as Write strobe for High Byte (WRH).
39	P2.0	O0 / I	St/B	Bit 0 of Port 2, General Purpose Input/Output
	AD13	OH / I	St/B	External Bus Interface Address/Data Line 13
	RxDC0C	I	St/B	CAN Node 0 Receive Data Input
40	P2.1	O0 / I	St/B	Bit 1 of Port 2, General Purpose Input/Output
	TxDC0	O1	St/B	CAN Node 0 Transmit Data Output
	AD14	OH / I	St/B	External Bus Interface Address/Data Line 14
	ESR1_5	I	St/B	ESR1 Trigger Input 5
	EX0AINA	I	St/B	External Interrupt Trigger Input
41	P2.2	O0 / I	St/B	Bit 2 of Port 2, General Purpose Input/Output
	TxDC1	O1	St/B	CAN Node 1 Transmit Data Output
	AD15	OH / I	St/B	External Bus Interface Address/Data Line 15
	ESR2_5	I	St/B	ESR2 Trigger Input 5
	EX1AINA	I	St/B	External Interrupt Trigger Input
42	P4.0	O0 / I	St/B	Bit 0 of Port 4, General Purpose Input/Output
	CC2_24	O3 / I	St/B	CAPCOM2 CC24IO Capture Inp./ Compare Out.
	$\overline{\text{CS0}}$	OH	St/B	External Bus Interface Chip Select 0 Output

Table 4 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
66	P2.10	O0 / I	St/B	Bit 10 of Port 2, General Purpose Input/Output
	U0C1_DOUT	O1	St/B	USIC0 Channel 1 Shift Data Output
	U0C0_SELO3	O2	St/B	USIC0 Channel 0 Select/Control 3 Output
	CC2_23	O3 / I	St/B	CAPCOM2 CC23IO Capture Inp./ Compare Out.
	A23	OH	St/B	External Bus Interface Address Line 23
	U0C1_DX0E	I	St/B	USIC0 Channel 1 Shift Data Input
	CAPIN	I	St/B	GPT2 Register CAPREL Capture Input
67	P10.3	O0 / I	St/B	Bit 3 of Port 10, General Purpose Input/Output
	CCU60_COUT60	O2	St/B	CCU60 Channel 0 Output
	AD3	OH / I	St/B	External Bus Interface Address/Data Line 3
	U0C0_DX2A	I	St/B	USIC0 Channel 0 Shift Control Input
	U0C1_DX2A	I	St/B	USIC0 Channel 1 Shift Control Input
68	P0.5	O0 / I	St/B	Bit 5 of Port 0, General Purpose Input/Output
	U1C1_SCLKOUT	O1	St/B	USIC1 Channel 1 Shift Clock Output
	U1C0_SELO2	O2	St/B	USIC1 Channel 0 Select/Control 2 Output
	CCU61_COUT62	O3	St/B	CCU61 Channel 2 Output
	A5	OH	St/B	External Bus Interface Address Line 5
	U1C1_DX1A	I	St/B	USIC1 Channel 1 Shift Clock Input
	U1C0_DX1C	I	St/B	USIC1 Channel 0 Shift Clock Input
69	P10.4	O0 / I	St/B	Bit 4 of Port 10, General Purpose Input/Output
	U0C0_SELO3	O1	St/B	USIC0 Channel 0 Select/Control 3 Output
	CCU60_COUT61	O2	St/B	CCU60 Channel 1 Output
	AD4	OH / I	St/B	External Bus Interface Address/Data Line 4
	U0C0_DX2B	I	St/B	USIC0 Channel 0 Shift Control Input
	U0C1_DX2B	I	St/B	USIC0 Channel 1 Shift Control Input

Table 4 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
70	P10.5	O0 / I	St/B	Bit 5 of Port 10, General Purpose Input/Output
	U0C1_SCLKOUT	O1	St/B	USIC0 Channel 1 Shift Clock Output
	CCU60_COUT62	O2	St/B	CCU60 Channel 2 Output
	AD5	OH / I	St/B	External Bus Interface Address/Data Line 5
	U0C1_DX1B	I	St/B	USIC0 Channel 1 Shift Clock Input
71	P0.6	O0 / I	St/B	Bit 6 of Port 0, General Purpose Input/Output
	U1C1_DOUT	O1	St/B	USIC1 Channel 1 Shift Data Output
	TxDC1	O2	St/B	CAN Node 1 Transmit Data Output
	CCU61_COUT63	O3	St/B	CCU61 Channel 3 Output
	A6	OH	St/B	External Bus Interface Address Line 6
	U1C1_DX0A	I	St/B	USIC1 Channel 1 Shift Data Input
	CCU61_CTRAPA	I	St/B	CCU61 Emergency Trap Input
	U1C1_DX1B	I	St/B	USIC1 Channel 1 Shift Clock Input
72	P10.6	O0 / I	St/B	Bit 6 of Port 10, General Purpose Input/Output
	U0C0_DOUT	O1	St/B	USIC0 Channel 0 Shift Data Output
	U1C0_SELO0	O3	St/B	USIC1 Channel 0 Select/Control 0 Output
	AD6	OH / I	St/B	External Bus Interface Address/Data Line 6
	U0C0_DX0C	I	St/B	USIC0 Channel 0 Shift Data Input
	U1C0_DX2D	I	St/B	USIC1 Channel 0 Shift Control Input
	CCU60_CTRAPA	I	St/B	CCU60 Emergency Trap Input

Table 4 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
79	P10.8	O0 / I	St/B	Bit 8 of Port 10, General Purpose Input/Output
	U0C0_MCLKOUT	O1	St/B	USIC0 Channel 0 Master Clock Output
	U0C1_SELO0	O2	St/B	USIC0 Channel 1 Select/Control 0 Output
	AD8	OH / I	St/B	External Bus Interface Address/Data Line 8
	CCU60_CCPOS1A	I	St/B	CCU60 Position Input 1
	U0C0_DX1C	I	St/B	USIC0 Channel 0 Shift Clock Input
	BRKIN_B	I	St/B	OCDS Break Signal Input
80	P10.9	O0 / I	St/B	Bit 9 of Port 10, General Purpose Input/Output
	U0C0_SELO4	O1	St/B	USIC0 Channel 0 Select/Control 4 Output
	U0C1_MCLKOUT	O2	St/B	USIC0 Channel 1 Master Clock Output
	AD9	OH / I	St/B	External Bus Interface Address/Data Line 9
	CCU60_CCPOS2A	I	St/B	CCU60 Position Input 2
	TCK_B	I	St/B	JTAG Clock Input
81	P1.1	O0 / I	St/B	Bit 1 of Port 1, General Purpose Input/Output
	CCU62_COUT62	O1	St/B	CCU62 Channel 2 Output
	U1C0_SELO5	O2	St/B	USIC1 Channel 0 Select/Control 5 Output
	U2C1_DOUT	O3	St/B	USIC2 Channel 1 Shift Data Output
	A9	OH	St/B	External Bus Interface Address Line 9
	ESR2_3	I	St/B	ESR2 Trigger Input 3
	EX1BINA	I	St/B	External Interrupt Trigger Input
	U2C1_DX0C	I	St/B	USIC2 Channel 1 Shift Data Input

General Device Information

Table 4 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
93	P1.6	O0 / I	St/B	Bit 6 of Port 1, General Purpose Input/Output
	CCU62_ CC61	O1 / I	St/B	CCU62 Channel 1 Input/Output
	U1C1_ SELO2	O2	St/B	USIC1 Channel 1 Select/Control 2 Output
	U2C0_DOUT	O3	St/B	USIC2 Channel 0 Shift Data Output
	A14	OH	St/B	External Bus Interface Address Line 14
	U2C0_DX0D	I	St/B	USIC2 Channel 0 Shift Data Input
94	P1.7	O0 / I	St/B	Bit 7 of Port 1, General Purpose Input/Output
	CCU62_ CC60	O1 / I	St/B	CCU62 Channel 0 Input/Output
	U1C1_ MCLKOUT	O2	St/B	USIC1 Channel 1 Master Clock Output
	U2C0_ SCLKOUT	O3	St/B	USIC2 Channel 0 Shift Clock Output
	A15	OH	St/B	External Bus Interface Address Line 15
	U2C0_DX1C	I	St/B	USIC2 Channel 0 Shift Clock Input
95	XTAL2	O	Sp/1	Crystal Oscillator Amplifier Output
96	XTAL1	I	Sp/1	Crystal Oscillator Amplifier Input To clock the device from an external source, drive XTAL1, while leaving XTAL2 unconnected. Voltages on XTAL1 must comply to the core supply voltage V_{DDI1} .
97	$\overline{\text{PORST}}$	I	In/B	Power On Reset Input A low level at this pin resets the XE164 completely. A spike filter suppresses input pulses <10 ns. Input pulses >100 ns safely pass the filter. The minimum duration for a safe recognition should be 120 ns. An internal pullup device will hold this pin high when nothing is driving it.

3.1 Memory Subsystem and Organization

The memory space of the XE164 is configured in the von Neumann architecture. In this architecture all internal and external resources, including code memory, data memory, registers and I/O ports, are organized in the same linear address space.

Table 5 XE164 Memory Map

Address Area	Start Loc.	End Loc.	Area Size ¹⁾	Notes
IMB register space	FF'FF00 _H	FF'FFFF _H	256 Bytes	–
Reserved (Access trap)	F0'0000 _H	FF'FEFF _H	<1 Mbyte	Minus IMB registers
Reserved for EPSRAM	E9'0000 _H	EF'FFFF _H	448 Kbytes	Mirrors EPSRAM
Emulated PSRAM	E8'0000 _H	E8'FFFF _H	64 Kbytes	Flash timing
Reserved for PSRAM	E1'0000 _H	E7'FFFF _H	448 Kbytes	Mirrors PSRAM
Program SRAM	E0'0000 _H	E0'FFFF _H	64 Kbytes	Maximum speed
Reserved for pr. mem.	CC'0000 _H	DF'FFFF _H	<1.25 Mbytes	–
Program Flash 2	C8'0000 _H	CB'FFFF _H	256 Kbytes	–
Program Flash 1	C4'0000 _H	C7'FFFF _H	256 Kbytes	–
Program Flash 0	C0'0000 _H	C3'FFFF _H	256 Kbytes	²⁾
External memory area	40'0000 _H	BF'FFFF _H	8 Mbytes	–
Available Ext. IO area ³⁾	20'5800 _H	3F'FFFF _H	< 2 Mbytes	Minus USIC/CAN
USIC registers	20'4000 _H	20'57FF _H	6 Kbytes	Accessed via EBC
MultiCAN registers	20'0000 _H	20'3FFF _H	16 Kbytes	Accessed via EBC
External memory area	01'0000 _H	1F'FFFF _H	< 2 Mbytes	Minus segment 0
SFR area	00'FE00 _H	00'FFFF _H	0.5 Kbyte	–
Dual-Port RAM	00'F600 _H	00'FDFF _H	2 Kbytes	–
Reserved for DPRAM	00'F200 _H	00'F5FF _H	1 Kbyte	–
ESFR area	00'F000 _H	00'F1FF _H	0.5 Kbyte	–
XSFR area	00'E000 _H	00'EFFF _H	4 Kbytes	–
Data SRAM	00'A000 _H	00'DFFF _H	16 Kbytes	–
Reserved for DSRAM	00'8000 _H	00'9FFF _H	8 Kbytes	–
External memory area	00'0000 _H	00'7FFF _H	32 Kbytes	–

1) The areas marked with “<” are slightly smaller than indicated. See column “Notes”.

2) The uppermost 4-Kbyte sector of the first Flash segment is reserved for internal use (C0'F000_H to C0'FFFF_H).

3) Several pipeline optimizations are not active within the external IO area. This is necessary to control external peripherals properly.

3.3 Central Processing Unit (CPU)

The core of the CPU consists of a 5-stage execution pipeline with a 2-stage instruction-fetch pipeline, a 16-bit arithmetic and logic unit (ALU), a 32-bit/40-bit multiply and accumulate unit (MAC), a register-file providing three register banks, and dedicated SFRs. The ALU features a multiply-and-divide unit, a bit-mask generator, and a barrel shifter.

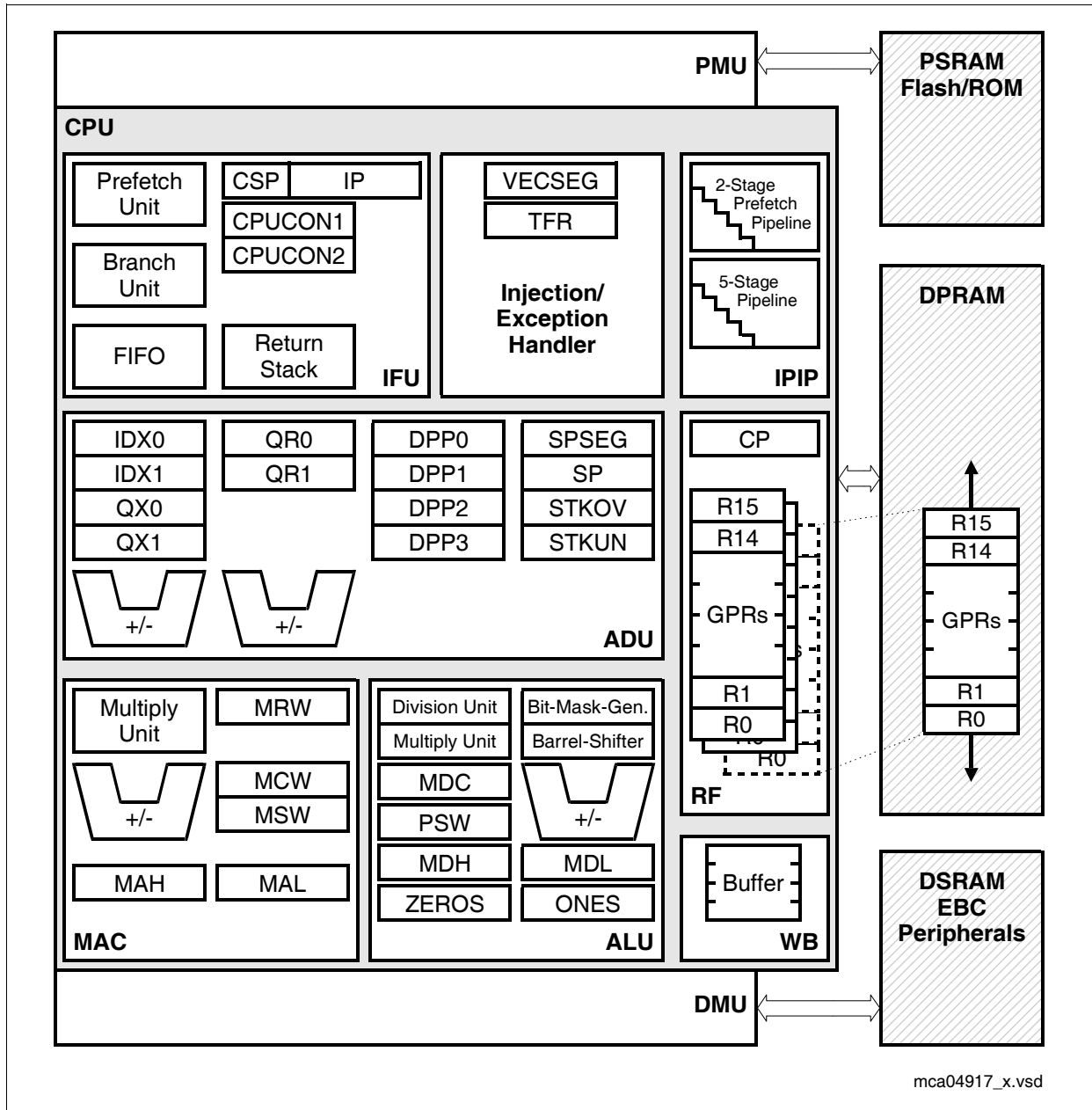


Figure 4 CPU Block Diagram

Functional Description

Table 6 XE164 Interrupt Nodes (cont'd)

Source of Interrupt or PEC Service Request	Control Register	Vector Location¹⁾	Trap Number
USIC2 Cannel 1, Request 0	U2C1_0IC	xx'017C _H	5F _H / 95 _D
USIC2 Cannel 1, Request 1	U2C1_1IC	xx'0180 _H	60 _H / 96 _D
USIC2 Cannel 1, Request 2	U2C1_2IC	xx'0184 _H	61 _H / 97 _D
Unassigned node	–	xx'0188 _H	62 _H / 98 _D
Unassigned node	–	xx'018C _H	63 _H / 99 _D
Unassigned node	–	xx'0190 _H	64 _H / 100 _D
Unassigned node	–	xx'0194 _H	65 _H / 101 _D
Unassigned node	–	xx'0198 _H	66 _H / 102 _D
Unassigned node	–	xx'019C _H	67 _H / 103 _D
Unassigned node	–	xx'01A0 _H	68 _H / 104 _D
Unassigned node	–	xx'01A4 _H	69 _H / 105 _D
Unassigned node	–	xx'01A8 _H	6A _H / 106 _D
SCU Request 1	SCU_1IC	xx'01AC _H	6B _H / 107 _D
SCU Request 0	SCU_0IC	xx'01B0 _H	6C _H / 108 _D
Program Flash Modules	PFM_IC	xx'01B4 _H	6D _H / 109 _D
RTC	RTC_IC	xx'01B8 _H	6E _H / 110 _D
End of PEC Subchannel	EOPIC	xx'01BC _H	6F _H / 111 _D

- 1) Register VECSEG defines the segment where the vector table is located.
 Bitfield VECSC in register CPUCON1 defines the distance between two adjacent vectors. This table represents the default setting with a distance of 4 (two words) between two vectors.

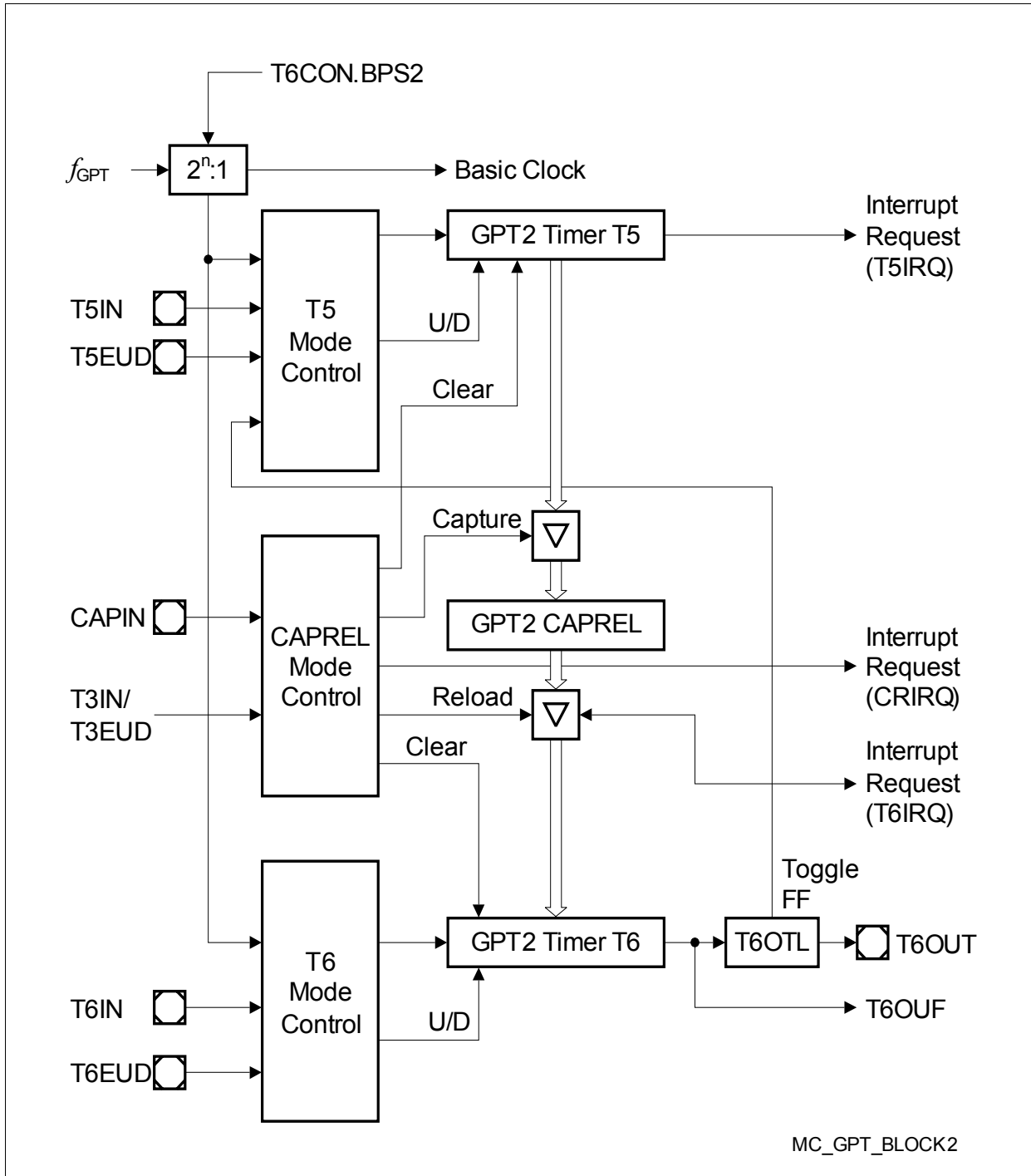


Figure 8 **Block Diagram of GPT2**

4 Electrical Parameters

The operating range for the XE164 is defined by its electrical parameters. For proper operation the specified limits must be respected during system design.

Note: Typical parameter values refer to room temperature and nominal supply voltage, minimum/maximum parameter values also include conditions of minimum/maximum temperature and minimum/maximum supply voltage. Additional details are described where applicable.

4.1 General Parameters

These parameters are valid for all subsequent descriptions, unless otherwise noted.

Table 11 Absolute Maximum Rating Parameters

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Storage temperature	T_{ST}	-65	–	150	°C	–
Junction temperature	T_J	-40	–	125	°C	under bias
Voltage on V_{DDI} pins with respect to ground (V_{SS})	V_{DDIM} , V_{DDI1}	-0.5	–	1.65	V	–
Voltage on V_{DDP} pins with respect to ground (V_{SS})	V_{DDPA} , V_{DDPB}	-0.5	–	6.0	V	–
Voltage on any pin with respect to ground (V_{SS})	V_{IN}	-0.5	–	$V_{DDP} + 0.5$	V	$V_{IN} < V_{DDPmax}$
Input current on any pin during overload condition	–	-10	–	10	mA	–
Absolute sum of all input currents during overload condition	–	–	–	100	mA	–
Output current on any pin	I_{OH} , I_{OL}	–	–	30	mA	–

Note: Stresses above the values listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for an extended time may affect device reliability. During absolute maximum rating overload conditions ($V_{IN} > V_{DDP}$ or $V_{IN} < V_{SS}$) the voltage on V_{DDP} pins with respect to ground (V_{SS}) must not exceed the values defined by the absolute maximum ratings.

4.2.3 Power Consumption

The power consumed by the XE164 depends on several factors such as supply voltage, operating frequency, active circuits, and operating temperature. The power consumption specified here consists of two components:

- The switching current I_S depends on the device activity
- The leakage current I_{LK} depends on the device temperature

To determine the actual power consumption, always both components, switching current I_S ([Table 16](#)) and leakage current I_{LK} ([Table 17](#)) must be added:

$$I_{DDP} = I_S + I_{LK}$$

Note: The power consumption values are not subject to production test. They are verified by design/characterization.

To determine the total power consumption for dimensioning the external power supply, also the pad driver currents must be considered.

The given power consumption parameters and their values refer to specific operating conditions:

- **Active mode:**
Regular operation, i.e. peripherals are active, code execution out of Flash.
- **Stopover mode:**
Crystal oscillator and PLL stopped, Flash switched off, clock in domain DMP_1 stopped.

Note: The maximum values cover the complete specified operating range of all manufactured devices.

The typical values refer to average devices under typical conditions, such as nominal supply voltage, room temperature, application-oriented activity.

After a power reset, the decoupling capacitors for V_{DDI} are charged with the maximum possible current, see parameter I_{CC} in [Table 20](#).

For additional information, please refer to [Section 5.2, Thermal Considerations](#).

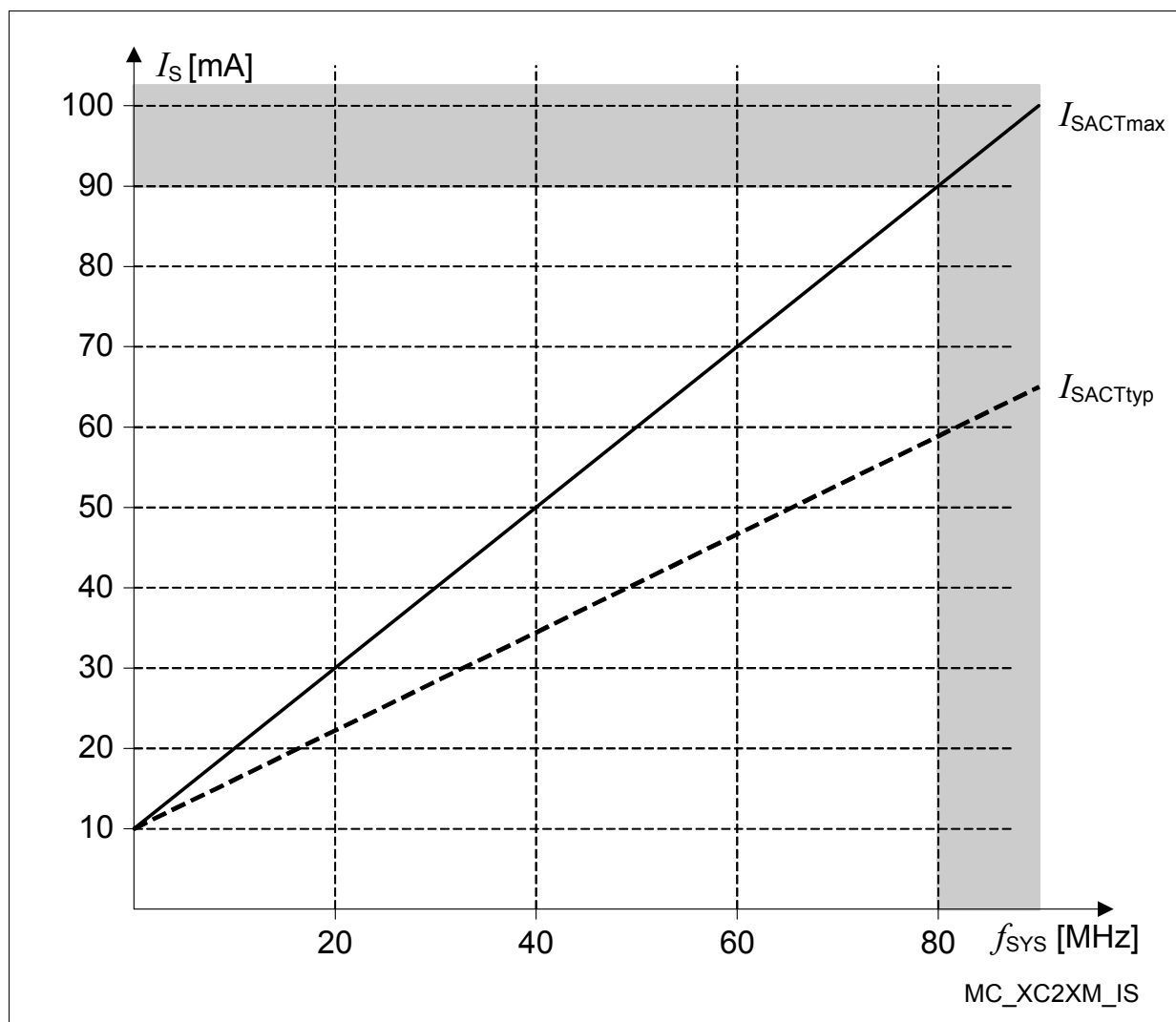


Figure 13 Supply Current in Active Mode as a Function of Frequency

Table 24 Flash Access Waitstates

Required Waitstates	System Frequency Range
4 WS (WSFLASH = 100 _B)	$f_{\text{SYS}} \leq f_{\text{SYSmax}}$
3 WS (WSFLASH = 011 _B)	$f_{\text{SYS}} \leq 17 \text{ MHz}$
2 WS (WSFLASH = 010 _B)	$f_{\text{SYS}} \leq 13 \text{ MHz}$
1 WS (WSFLASH = 001 _B)	$f_{\text{SYS}} \leq 8 \text{ MHz}$
0 WS (WSFLASH = 000 _B)	Forbidden! Must not be selected!

Note: The maximum achievable system frequency is limited by the properties of the respective derivative.

Electrical Parameters

The timing in the AC Characteristics refers to TCSs. Timing must be calculated using the minimum TCS possible under the given circumstances.

The actual minimum value for TCS depends on the jitter of the PLL. Because the PLL is constantly adjusting its output frequency to correspond to the input frequency (from crystal or oscillator), the accumulated jitter is limited. This means that the relative deviation for periods of more than one TCS is lower than for a single TCS (see formulas and [Figure 19](#)).

This is especially important for bus cycles using waitstates and for the operation of timers, serial interfaces, etc. For all slower operations and longer periods (e.g. pulse train generation or measurement, lower baudrates, etc.) the deviation caused by the PLL jitter is negligible.

The value of the accumulated PLL jitter depends on the number of consecutive VCO output cycles within the respective timeframe. The VCO output clock is divided by the output prescaler K2 to generate the system clock signal f_{SYS} . The number of VCO cycles is $K2 \times T$, where T is the number of consecutive f_{SYS} cycles (TCS).

The maximum accumulated jitter (long-term jitter) D_{Tmax} is defined by:

$$D_{Tmax} [ns] = \pm(220 / (K2 \times f_{SYS}) + 4.3)$$

This maximum value is applicable, if either the number of clock cycles $T > (f_{SYS} / 1.2)$ or the prescaler value $K2 > 17$.

In all other cases for a timeframe of $T \times TCS$ the accumulated jitter D_T is determined by:

$$D_T [ns] = D_{Tmax} \times [(1 - 0.058 \times K2) \times (T - 1) / (0.83 \times f_{SYS} - 1) + 0.058 \times K2]$$

f_{SYS} in [MHz] in all formulas.

Example, for a period of 3 TCSs @ 33 MHz and $K2 = 4$:

$$D_{max} = \pm(220 / (4 \times 33) + 4.3) = 5.97 \text{ ns (Not applicable directly in this case!)}$$

$$\begin{aligned} D_3 &= 5.97 \times [(1 - 0.058 \times 4) \times (3 - 1) / (0.83 \times 33 - 1) + 0.058 \times 4] \\ &= 5.97 \times [0.768 \times 2 / 26.39 + 0.232] \\ &= 1.7 \text{ ns} \end{aligned}$$

Example, for a period of 3 TCSs @ 33 MHz and $K2 = 2$:

$$D_{max} = \pm(220 / (2 \times 33) + 4.3) = 7.63 \text{ ns (Not applicable directly in this case!)}$$

$$\begin{aligned} D_3 &= 7.63 \times [(1 - 0.058 \times 2) \times (3 - 1) / (0.83 \times 33 - 1) + 0.058 \times 2] \\ &= 7.63 \times [0.884 \times 2 / 26.39 + 0.116] \\ &= 1.4 \text{ ns} \end{aligned}$$

**Table 30 External Bus Cycle Timing for Lower Voltage Range
(Operating Conditions apply)**

Parameter	Symbol	Limits			Unit	Note
		Min.	Typ.	Max.		
Output valid delay for: $\overline{\text{RD}}$, $\overline{\text{WR}}(\text{L}/\text{H})$	t_{10} CC	–		20	ns	
Output valid delay for: $\overline{\text{BHE}}$, ALE	t_{11} CC	–		20	ns	
Output valid delay for: A23 ... A16, A15 ... A0 (on P0/P1)	t_{12} CC	–		22	ns	
Output valid delay for: A15 ... A0 (on P2/P10)	t_{13} CC	–		22	ns	
Output valid delay for: $\overline{\text{CS}}$	t_{14} CC	–		20	ns	
Output valid delay for: D15 ... D0 (write data, MUX-mode)	t_{15} CC	–		21	ns	
Output valid delay for: D15 ... D0 (write data, DEMUX-mode)	t_{16} CC	–		21	ns	
Output hold time for: $\overline{\text{RD}}$, $\overline{\text{WR}}(\text{L}/\text{H})$	t_{20} CC	0		10	ns	
Output hold time for: $\overline{\text{BHE}}$, ALE	t_{21} CC	0		10	ns	
Output hold time for: A23 ... A16, A15 ... A0 (on P2/P10)	t_{23} CC	0		10	ns	
Output hold time for: $\overline{\text{CS}}$	t_{24} CC	0		10	ns	
Output hold time for: D15 ... D0 (write data)	t_{25} CC	0		10	ns	
Input setup time for: READY, D15 ... D0 (read data)	t_{30} SR	29		–	ns	
Input hold time for: READY, D15 ... D0 (read data) ¹⁾	t_{31} SR	-6		–	ns	

1) Read data are latched with the same internal clock edge that triggers the address change and the rising edge of $\overline{\text{RD}}$. Address changes before the end of $\overline{\text{RD}}$ have no impact on (demultiplexed) read cycles. Read data can change after the rising edge of $\overline{\text{RD}}$.

Table 32 SSC Master/Slave Mode Timing for Lower Voltage Range
(Operating Conditions apply), $C_L = 50 \text{ pF}$

Parameter	Symbol	Values			Unit	Note / Test Co ndition
		Min.	Typ.	Max.		
Master Mode Timing						
Slave select output SELO active to first SCLKOUT transmit edge	t_1 CC	0	—	1)	ns	2)
Slave select output SELO inactive after last SCLKOUT receive edge	t_2 CC	$0.5 \times t_{\text{BIT}}$	—	3)	ns	2)
Transmit data output valid time	t_3 CC	-13	—	16	ns	
Receive data input setup time to SCLKOUT receive edge	t_4 SR	48	—	—	ns	
Data input DX0 hold time from SCLKOUT receive edge	t_5 SR	-11	—	—	ns	
Slave Mode Timing						
Select input DX2 setup to first clock input DX1 transmit edge	t_{10} SR	12	—	—	ns	4)
Select input DX2 hold after last clock input DX1 receive edge	t_{11} SR	8	—	—	ns	4)
Data input DX0 setup time to clock input DX1 receive edge	t_{12} SR	12	—	—	ns	4)
Data input DX0 hold time from clock input DX1 receive edge	t_{13} SR	8	—	—	ns	4)
Data output DOUT valid time	t_{14} CC	11	—	44	ns	4)

- 1) The maximum value further depends on the settings for the slave select output leading delay.
- 2) $t_{\text{SYS}} = 1/f_{\text{SYS}} (= 12.5 \text{ ns @ } 80 \text{ MHz})$
- 3) The maximum value depends on the settings for the slave select output trailing delay and for the shift clock output delay.
- 4) These input timings are valid for asynchronous input signal handling of slave select input, shift clock input, and receive data input (bits DXnCR.DSEN = 0).